



Product Information Sheet

EPO-TEK® B9126-7

Date: May 2020
Rev: IV
No. of Components: Single
Mix Ratio by Weight: N/A
Specific Gravity: 1.32
Pot Life: 3 Days
Shelf Life- Bulk: Six months refrigerated

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s):
May not achieve performance properties listed below
 150°C / 5 Minutes
 120°C / 15 Minutes

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Product is shipped on dry ice and can be refrigerated upon receipt. Failure to ship frozen may result in viscosity growth beyond the range of values herein.

Product Description: A single component, thermally conductive, electrically insulating epoxy adhesive designed for semiconductor die attach and circuit assembly applications. Its unique features are a low temperature cure and syringe dispensing rheology. It can be used for thermal dissipation when bonding chips, SMDs, PCBs or heat sinks.

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Light yellow		
* Consistency:	Smooth paste		
* Viscosity (23°C) @ 10 rpm:	25,000-35,000	cPs	
Thixotropic Index:	2.8		
* Glass Transition Temp:	≥ 55	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):			
	Below Tg:	63	x 10 ⁻⁶ in/in°C
	Above Tg:	202	x 10 ⁻⁶ in/in°C
Shore D Hardness:	77		
Lap Shear @ 23°C:	1,180	psi	
Die Shear @ 23°C:	≥ 10	Kg	3,556 psi
Degradation Temp:	381 °C		
Weight Loss:			
	@ 200°C:	0.31	%
	@ 250°C:	0.78	%
	@ 300°C:	1.91	%
Suggested Operating Temperature:	< 300 °C (Intermittent)		
Storage Modulus:	413,439	psi	
* Particle Size:	≤ 20	microns	

ELECTRICAL AND THERMAL PROPERTIES:			
Thermal Conductivity:	0.6	W/mK	
Volume Resistivity @ 23°C:	≥ 5 x 10 ¹³	Ohm-cm	
Dielectric Constant (1KHz):	4.21		
Dissipation Factor (1KHz):	0.016		

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

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